# DZ2J051

### Silicon epitaxial planar type

For constant voltage / waveform clipper and surge absorption circuit Low noise type

#### Features

- $\bullet$  Excellent rising characteristics of zener current  $I_{\rm z}$
- Eco-friendly Halogen-free package

### Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit
Repetitive peak forward current	I <sub>FRM</sub>	200	mA
Total power dissipation *	P <sub>T</sub>	200	mW
Junction temperature	Tj	150	°C
Storage temperature	T <sub>stg</sub>	-55 to +150	°C

Note) \*:  $P_T = 200 \text{ mW}$  achieved with a printed circuit board.

#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V <sub>F</sub>	$I_F = 10 \text{ mA}$			1.0	V
Zener voltage *1, 2, 4	VZ	$I_Z = 5 \text{ mA}$	4.85		5.36	V
Zener operating resistance	R <sub>Z</sub>	$I_Z = 5 \text{ mA}$			60	Ω
Zener rise operating resistance	R <sub>ZK</sub>	$I_{Z} = 1.0 \text{ mA}$			500	Ω
Reverse current	I <sub>R</sub>	$V_{\rm R} = 2.0  {\rm V}$			1.0	μΑ
Temperature coefficient of zener voltage *3	Sz	$I_Z = 5 \text{ mA}$		0.7		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 5 MHz.

3. \*1: The temperature must be controlled 25°C for  $V_Z$  measurement.  $V_Z$  value measured at other temperature must be adjusted to  $V_Z$  (25°C) \*2:  $V_Z$  guaranteed 20 ms after current flow.

\*3:  $T_i = 25^{\circ}C$  to 150°C

\*4: Rank classification

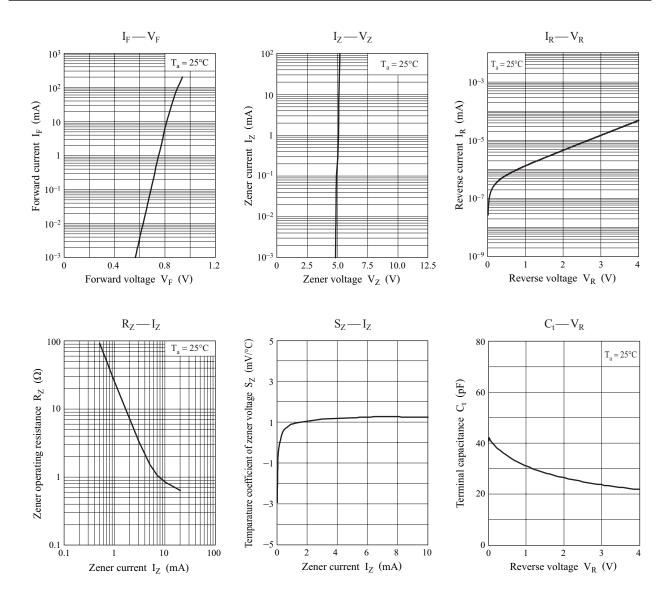
Code	М	0
Rank	М	No-rank
Vz	5.00 to 5.26	4.85 to 5.36
Marking Symbol	CU	СЈ

### Package

- Code
- SMini2-F5-B
- Pin Name
  - 1. Cathode
  - 2. Anode
- Marking Symbol: CJ, CU

### DZ2J051

# **Panasonic**

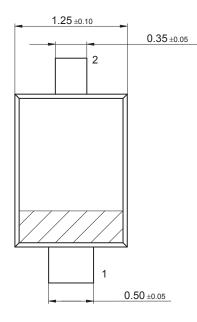


# **Panasonic**

# SMini2-F5-B

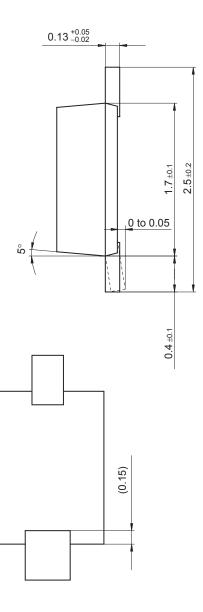
5

Unit: mm



0.7 ±0.1

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